

## **ABSTRACT OF THE DISCLOSURE**

A semiconductor device, comprising:

a semiconductor substrate providing a semiconductor element; and

5 a hard film which covers a part or the entirety of a side of the semiconductor substrate and which has top and bottom surfaces in approximately the same planes as those of the top and bottom surfaces of the semiconductor substrate,

wherein the side of the semiconductor substrate  
10 covered with the hard film is processed so as to be perpendicular or substantially perpendicular to the surface of the semiconductor substrate.